## MA2SD29

### Silicon epitaxial planar type

#### For super high speed switching

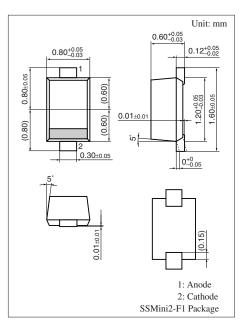
#### ■ Features

- Low forward voltage:  $V_F < 0.42 \text{ V}$  (at  $I_F = 100 \text{ mA}$ )
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>.

#### ■ Absolute Maximum Ratings T<sub>a</sub> = 25°C

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	30	V
Repetitive peak reverse voltage	$V_{RRM}$	30	V
Forward current (Average)	I <sub>F(AV)</sub>	100	mA
Peak forward current	$I_{FM}$	200	mA
Non-repetitive peak forward	$I_{FSM}$	1	A
surge current *			
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



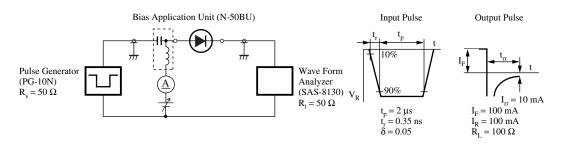
Marking Symbol: 8M

#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

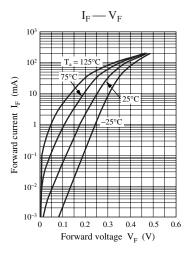
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I <sub>R1</sub>	$V_R = 10 \text{ V}$			25	μΑ
	I <sub>R2</sub>	$V_R = 30 \text{ V}$			120	
Forward voltage	$V_{F1}$	$I_F = 10 \text{ mA}$		0.25	0.29	V
	$V_{F2}$	$I_F = 100 \text{ mA}$		0.39	0.42	
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		11		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$				

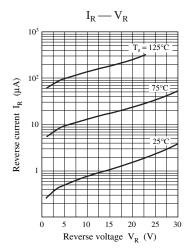
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

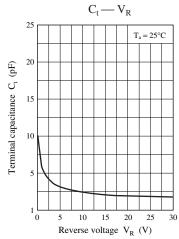
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz
- 4. \*: t<sub>rr</sub> measurement circuit



## **Panasonic**







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